

# Specification of Thermoelectric Module

## TES1-09521L1

### Description

The 95 couples, 10mm x 30mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

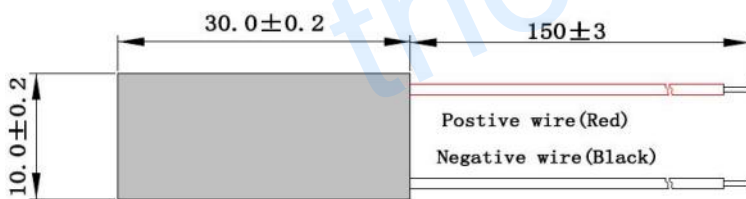
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

|                            |      |      |   |
|----------------------------|------|------|---|
| Th (°C)                    | 27   | 50   | Hot side temperature at environment: dry air, N <sub>2</sub>  |
| DT <sub>max</sub> (°C)     | 70   | 79   | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |
| U <sub>max</sub> (Voltage) | 11.8 | 12.7 | Voltage applied to the module at DT <sub>max</sub>  |
| I <sub>max</sub> (Amps)    | 2.36 | 2.36 | DC current through the modules at DT <sub>max</sub>   |
| Q <sub>Cmax</sub> (Watts)  | 17.9 | 19.3 | Cooling capacity at cold side of the module under DT=0 °C   |
| AC resistance (Ohms)       | 3.76 | 4.05 | The module resistance is tested under AC  |
| Tolerance (%)              | 10%  |      | For thermal and electricity parameters  |

### Geometric Characteristics Dimensions in millimeters



### Manufacturing Options

#### A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

#### B. Sealant:

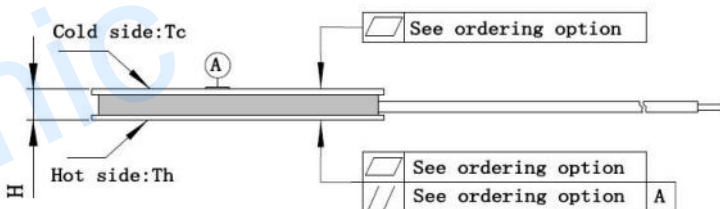
1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized



### Ordering Option

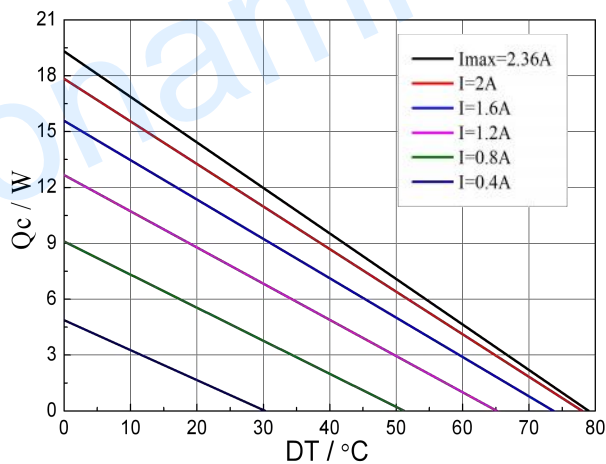
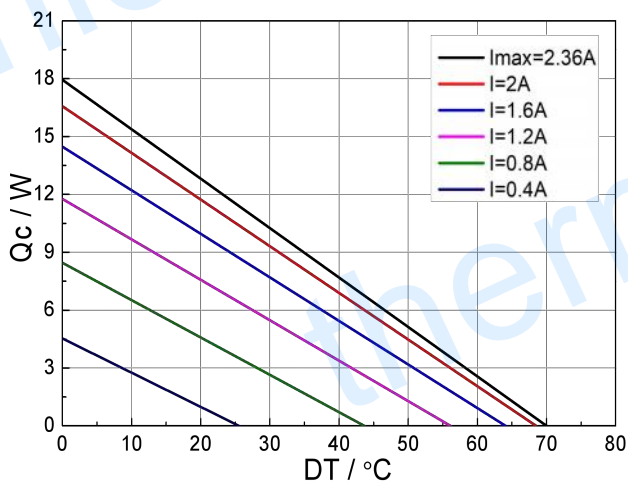
| Suffix | Thickness H (mm) | Flatness/ Parallelism (mm) | Lead wire length(mm)<br>Standard/Optional length |
|--------|------------------|----------------------------|--|
| TF     | 0:3.04 ± 0.07    | 0: 0.06/0.06               | 150±3/Specify                                    |
| TF     | 1:3.04 ± 0.03    | 1: 0.03/0.03               | 150±3/Specify                                    |

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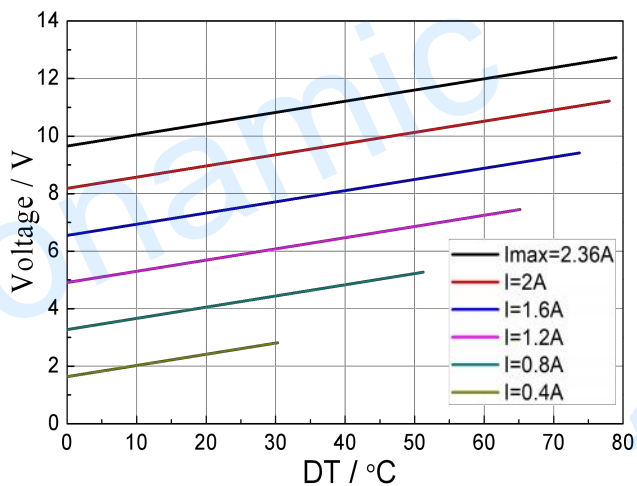
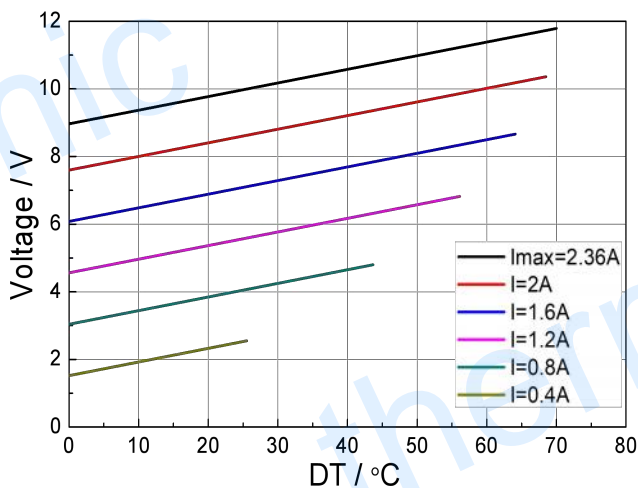
**TES1-09521L1**

**Performance Curves at Th=27 °C**

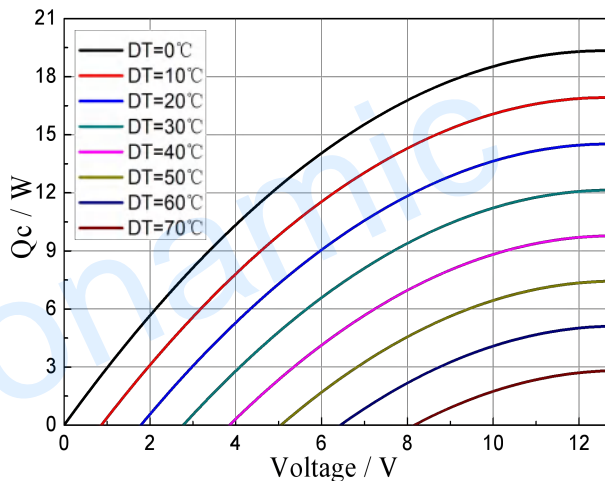
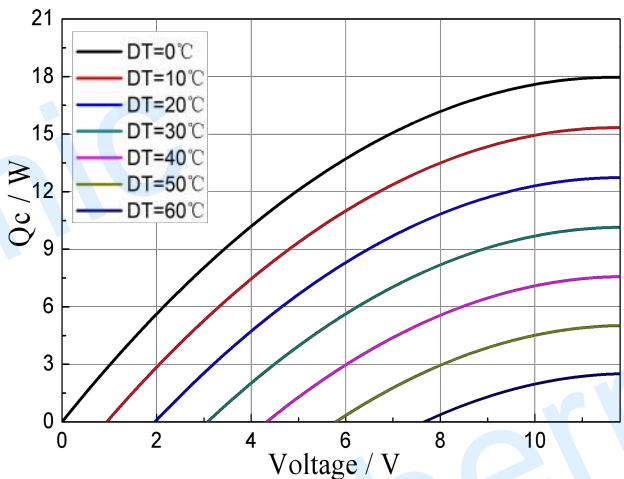
**Performance Curves at Th=50 °C**



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

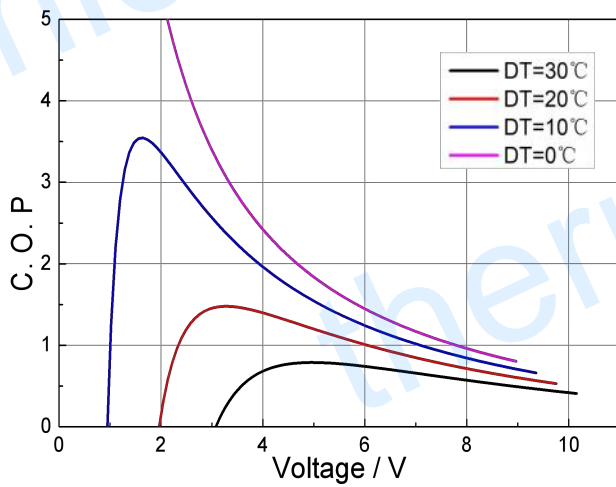


Standard Performance Graph  $Q_c = f(V)$

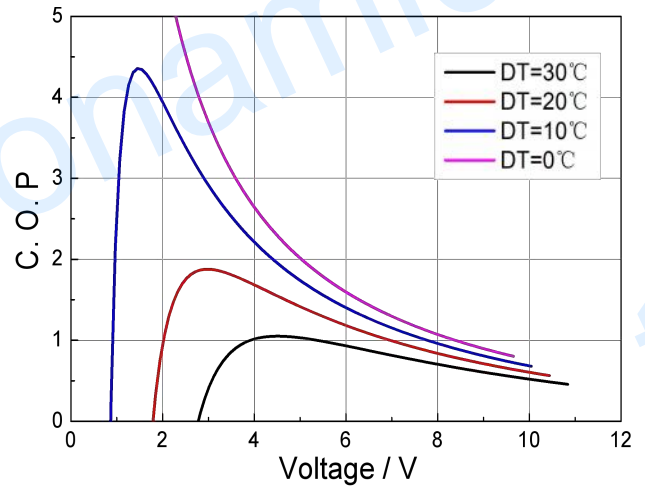
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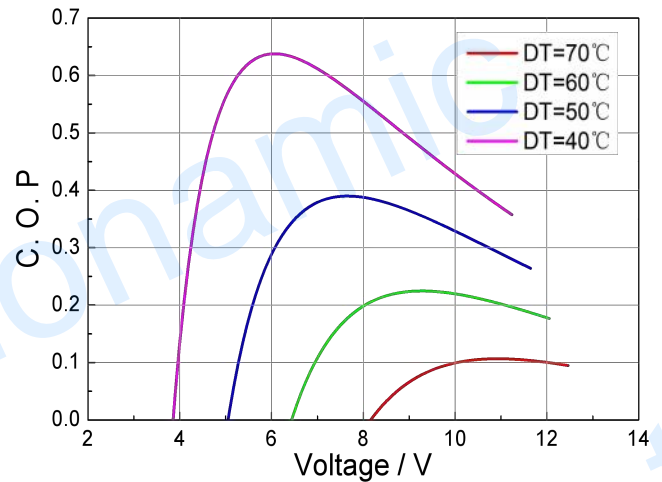
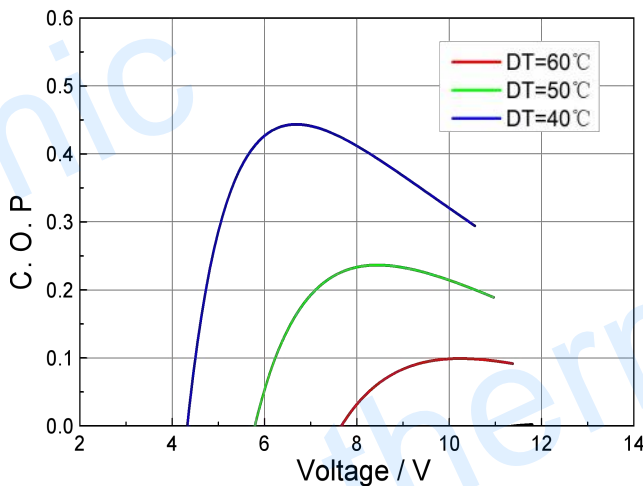
## Performance Curves at Th=27 °C



## Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

## Operation Caution

- Cold side of the module stucked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.